



Industry 4.0 and Smart Materials Processing for Enhanced Manufacturing

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Deadline for manuscript
submissions:

closed (30 April 2024)

Message from the Guest Editor

This Special Issue aims to showcase the latest research and developments in Industry 4.0 and smart materials processing for enhanced manufacturing. This Special Issue seeks to bring together contributions that address the challenges and opportunities of using Industry 4.0 and smart materials processing to support manufacturing processes. The purpose of this Special Issue is to provide a comprehensive overview of the latest research and practical applications of Industry 4.0 and smart materials processing in the manufacturing sector.

Topics of interest include but are not limited to:

- Additive manufacturing and 3D printing technologies for smart materials processing;
- Cyber-physical systems and the Industrial Internet of Things (IIoT) in Industry 4.0;
- Robotics and automation for smart materials processing;
- Smart sensors and data analytics for process monitoring and optimization;
- Digital twin and virtual reality for manufacturing simulations and design;
- Sustainable manufacturing and green technologies for Industry 4.0;
- Materials innovation and advances in smart materials processing.





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Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (JMMP) (ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to *JMMP*.

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Journal Rank: CiteScore - Q1 (*Mechanical Engineering*)

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Materials Processing* Editorial Office
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